

S/N: 09/832,884

12/18/2002

DOCKET NO.: L/M-102-DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of: St v M. Danziger, t al.

Serial No.: 09/832,884

Art Unit: 2829

Divisional of 09/321,565

Filed: April 12, 2001

Examiner: Evan T. Pert

For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects

AMENDMENT

Assistant Commissioner of
Patents and Trademarks
Washington, D.C. 20231

Box: Non-Fee Amendments

Sir:

This Amendment is responsive to the Office Action dated
September 24, 2002. Claims 1 - 10 are pending in this application.
Applicant hereby requests re-examination in light of the foregoing
amendments in the claims.

Please amend this application as follows:

IN THE CLAIMS:

Please cancel claim 9.

Please amend claims 1 - 8 and 10 as follows:

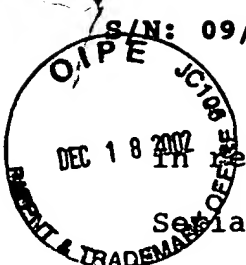
1. (Twice Amended) A known good die (KGD) having optional solder
ball array or wire bond connections;
solder ball array connections on the known good die surface;

TECHNOLOGY CENTER 2800

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